Contact Name Title - Contact Product-Env-Stewards Product-Enviro Compliance NA Product-Env-Stewards	ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
Company name* Company name* Company unique ID Unique ID Authority Response Date* 2023-06-08 Contact Name Title - Contact* Phone - Contact* Product-Env-Stewards Produc	752-21.1											als and Mf	g Informati	on	
nsemi Contact Name Froduct Env-Stewards Product Enviro Compliance NA Product Env-Stewards@onsemi.com Inthorized Representative* Title - Representative Phone - Representative* Phone - Representative* Product Env-Stewards Product Enviro Compliance NA Product Env-Stewards@onsemi.com Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM Unit	upplier Informa	ntion													
Title - Contact Name Product Envisewards Prod	Company name*			Company unique ID			J	Unique ID Authority				Response Date*			
Product-Env-Stewards	nsemi											2023-06-08			
Authorized Representative* Product-Env-Stewards Product Enviro Compliance Requester Item Number Requester Ite	Contact Name			Title - Contact			I	Phone - Contact*				Email - Contact*			
Product Envi-Stewards Requester Item Number Mfr Item Number MG74HC11ADG DUAL J-K FLIP FLOP DUAL J-K F	Product-Env-Stewar	ds		Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com			
Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM Unit MC74HC11ADG DUAL J-K FLIP FLOP 2023-06-08 PH1 122.04 mg Each Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3 Seconds Comments Commen	uthorized Represen	tative*		Title - Representative			I	Phone - Representative*			Email - Representative*				
MC74HC11ADG DUAL J-K FLIP FLOP 2023-06-08 PH1 122.04 mg Each Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Seconds 3 Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3	Product-Env-Stewar	ds		Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com			
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	•	(Sn) - annealed	C	U Alloy	1			200		JC	30	second	s 3		
ver 1 - maximum ume at peak temperature during soldering is 10-30 seconds			J	J! ! 10 1	20 1-										
or more information regarding material composition please refer to page 3		·													

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose al applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.98	mg	Supplier	Silicon (Si)	7440-21-3		0.98	mg
Die Attach	4.44	mg	Supplier	Silver (Ag)	7440-22-4		3.33	mg
			Supplier	Epoxy resins	129915-35-1		1.11	mg
Lead Frame	69.62		Supplier	Silver (Ag)	7440-22-4		0.7658	mg
			Supplier	Zinc (Zn)	7440-66-6		0.1392	mg
			Supplier	Iron (Fe)	7439-89-6		1.8101	mg
			Supplier	Copper (Cu)	7440-50-8		66.9048	mg
Mold Compound-Black	43.43	mg		Epoxy resin	proprietary data		2.1715	mg
			Supplier	Phenolic Resin	Proprietary Data		2.1715	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.8686	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2172	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		38.0013	mg
Plating	3.27	mg	Supplier	Tin (Sn)	7440-31-5		3.27	mg
Wire Bond - Cu	0.3	mg	Supplier	Copper (Cu)	7440-50-8		0.3	mg